

Operation: 12PIN-SMT 板上卧贴式/双螺孔 结构防水型 & 2.0 Type-C 连接器

TDI 认证 IP66 防水

ITEM NO.: MC-311FN

(L8.00mm × W9.40mm × H4.00mm CONNECTORS)



Technical parameter

LEVEL		A[better product]	B[average product]
PROJECT			
Electrical Properties	Contact Rating	5.0A, 12V DC	
	Initial Contact Resistance	30mΩ max.	50mΩ max.
	Insulation Resistance	100MΩ min.500V DC	Skey/PD: 100MΩ min.300V DC
	Withstand Voltage	500V AC for 1 minute	350 V AC for 1 minut
Durable Performance	There No Load	10,000 Cycles	8,000 Cycles
	Rated Load	8,500 Cycles	6,500 Cycles
	Storage temp.	-35℃~+75℃(Operating Temp:)	

表面贴装 SMT

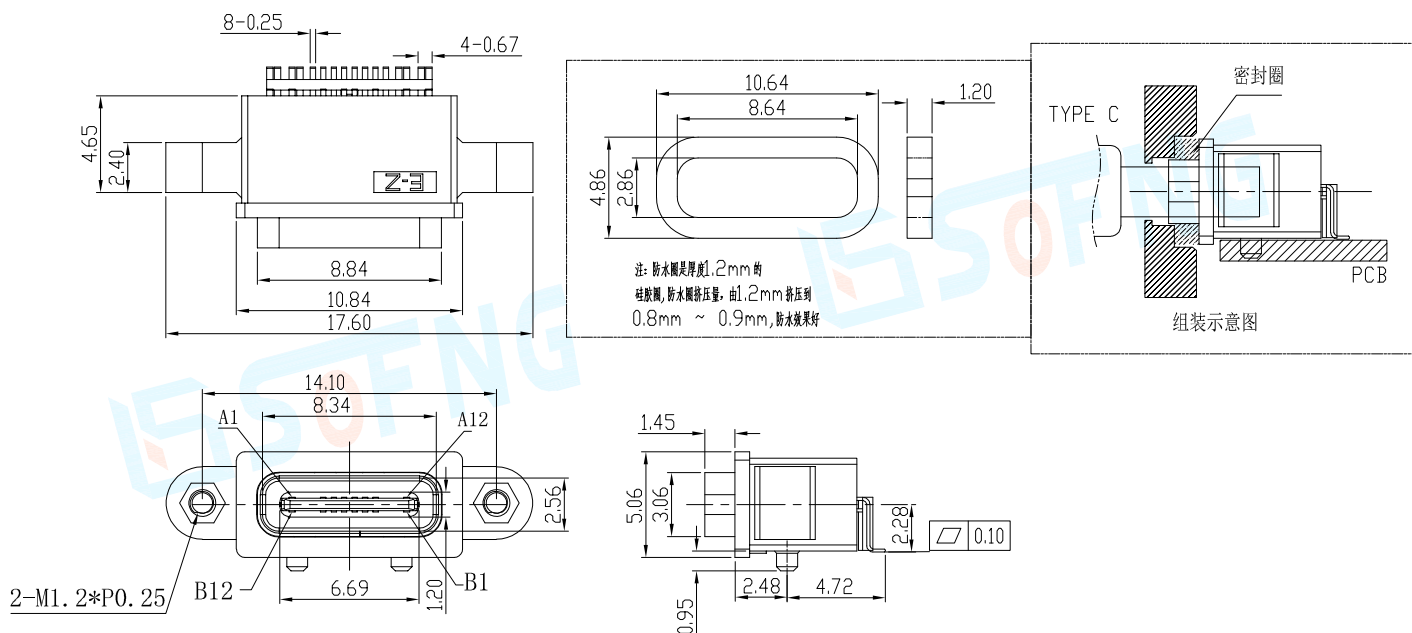
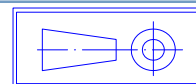
側向導入 LATERAL

精密部品 NICETY

可靠 STABILIZE

適合環保 RoHS

Unit:mm



Material declaration

No.	NAME	MATERIAL	DESCRIPTION
① A	SHIELDING PLATE 屏蔽壳	STAINLESS STEE	【G/F】0.25 μm Ni PLATED OVERALL;
② B	OVAL RING 防水圈	RUBBER	软橡胶
③ C	SHELL 外壳	STAINLESS STEE	【G/F】0.25 μm Ni PLATED OVERALL;
④ D	GND RING 接地件	STAINLESS STEE	STAINLESS STEEL;
⑤ E	CPSP 中隔钢片	STAINLESS STEE	STAINLESS STEEL;
⑥ F	HOUSING 基座	THERMOPLASTIC	UL 94V-0,COLOR:BLACK;
⑦ G	TERMINAL 接触端子	COPPER ALLOY 【G/F】	2.0 μm Ni PLATED OVERALL 0.25 μm Au PLATED CONTACT AREA GOLD FLASH ON SOLDER AREA
⑧ H	TERMINAL 接触端子	COPPER ALLOY 【G/F】	2.0 μm Ni PLATED OVERALL 0.25 μm Au PLATED CONTACT AREA GOLD FLASH ON SOLDER AREA

推荐锡膏厚度

0.12mm



Operating Force

Inward

5.0~12.0N. (1N.=100gram-force)

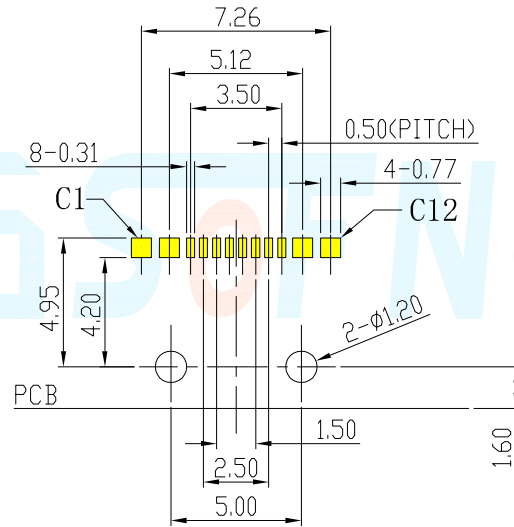
Exiting

5.0~12.0N. (1N.=100gram-force)

Solder-ability (Max.)

IR Reflow:255℃, 5sec.

Manual:350℃, 3sec.



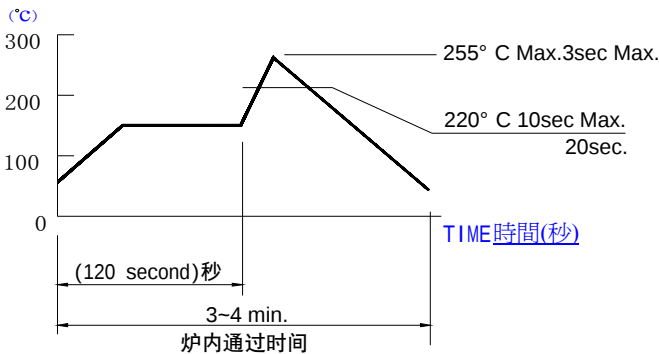
Pin Definition

DECIMALS	ANGLES
.X :±0.25	X.° :±1.5°
.XX :±0.15	X.X° :±1.0°
.XXX :±0.10	.XXX° :±0.5°

PIN NO.	A1&B12	A4&B9	B8	A5	B7	A6	A7	B6	A8	B5	A9&B4	A12&B1
SINGAL NAME	GND	VBUS	SBU2	CC1	DN2	DP1	DN1	DP2	SBU1	CC2	VBUS	GND
PCB PAD NO.	C1	C2	C3	C4	C5	C6	C7	C8	C9	C10	C11	C12

Please practice according to below condition:

- (1) Preheat :150 ℃ 90-120s
- (2) Soldering heat : 255 ℃ Max 10S.
- (3) Immersion depth: Up to the surface of the board

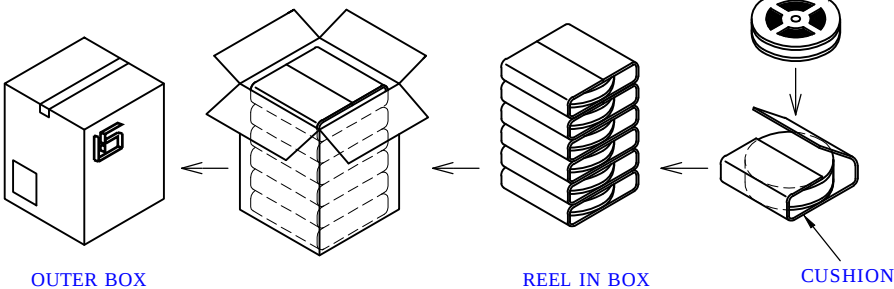


手焊接时

项目	条件
焊接温度	350℃ max.
连续焊接时间	3s max.
焊剂斗容量	60W max.

自动浸焊时

项目	条件
助焊剂附着量	不附着于零部件贴装面的程度
预热温度	印刷电路板焊接面的周围温度 100℃ max.
预热温度时间	60s max.
焊接温度	260℃ max.
焊接浸渍时间	5s max.
焊接次数	2次以下



OUTER BOX

REEL IN BOX

CUSHION

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